

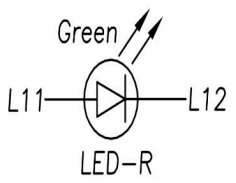
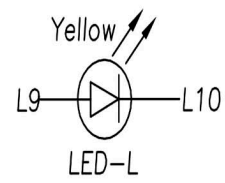
**ELECTRICAL SPECIFICATIONS@25°C UNLESS OTHERWISE NOTED:**

**NOTES:**

1. MATERIAL
  - 1.1 HOUSING:HIGH THERMAL PLASTIC,BLACK,UL94 V-0
  - 1.2 CONTACT:COPPER ALLOY,CONTACT AREA:PLATING G/F,  
SOLDER AREA:PLATING SN 80U"MIN.
  - 1.3 SHELL:COPPER ALLOY,PLATING NI 30U"MIN.
  - 1.4 LED:GREEN AND YELLOW
2. ELECTRICAL:
  - 2.1 CURRENT RATING: 1.5A MAX.
  - 2.2 VOLTAGE RATING :150V AC MIN. (RMS)
  - 2.3 WITHSTANDING VOLTAGE: 1000V AC FOR 1 MINUTE
  - 2.4 INSULATION RESISTANCE: 500MΩ MIN.
  - 2.5 CONTACT RESISTANCE: 40mΩ MAX.
3. ENVIRONMENTAL:
 

OPERATING TEMPERATURE: -40°C TO +85°C

*Recommended PCB Layout  
(T=1.0~1.2mm,Tol:±0.05)*



RoHS Compliant		HSM 玄茂科技股份有限公司 HSUAN MAO TECHNOLOGY CO., LTD.	
APPD. 核准		TOLERANCE .X±0.38	PART NAME 品名 SIDE ENTRY MODULAR JACK OFFSET TYPE 8P8C DIP TYPE WITH SHIELDED WITH LED (LEFT:YELLOW/RIGHT:GREEN) BLACK COLOR TRAY PACKING ROHS
DWG. 製圖 Betty	SCALE 比例 參考	.XX±0.25	PART NO. C0069-88YX02B0R
DATE 制表日 2021/12/20	UNIT 單位 MM	SIZE. 紙張尺寸 A4	料號
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